

L Number	Hits	Search Text	DB	Time stamp
102	963	438/629	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:54
103	2404	438/637	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:55
104	0	jp357104234a	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:55
105	326	438/667	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:55
106	312	438/668	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:56
107	1226	438/672	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:56
108	904	438/675	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:56
109	2690	438/629 438/667 438/668 438/672 438/675	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:57
110	63	(438/629 438/667 438/668 438/672 438/675) and (laser near1 beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 14:58
111	63	((438/629 438/667 438/668 438/672 438/675) and (laser near1 beam)) and (method process)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 15:33
112	0	6424048.URPN.	USPAT	2003/02/28 15:04
113	3	("5229647" "6072236" "6087719").PN.	USPAT	2003/02/28 15:04
114	2	6130111.URPN.	USPAT	2003/02/28 15:12
115	16	("3560257" "4499655" "4733291" "4991090" "5065228" "5198695" "5229647" "5325265" "5386142" "5399898" "5404044" "5406125" "5530288" "5552633" "5825080" "6063646").PN.	USPAT	2003/02/28 15:13
117	26	6114240.URPN.	USPAT	2003/02/28 15:15
118	3	("5322816" "5405805" "5496755").PN.	USPAT	2003/02/28 15:22
119	1	6110825.URPN.	USPAT	2003/02/28 15:23
120	26	5599744.URPN.	USPAT	2003/02/28 15:25
121	40	("3648131" "4499655" "4534100" "4784970" "4794092" "4830878" "4907128" "4954458" "4988641" "4992908" "5010025" "5013687" "5013919" "5030828" "5036203" "5045907" "5053350" "5064771" "5067233" "5075201" "5075238" "5093708" "5108938" "5122851" "5128749" "5135556" "5138164" "5149671" "5166097" "5208478" "5209798" "5231304" "5285570" "5292624" "5315147" "5334558" "5365790" "5393696" "5399898" "5510655").PN.	USPAT	2003/02/28 15:27
122	30	4978639.URPN.	USPAT	2003/02/28 15:30

123	439	substrate with ((through adj hole) vias opening) with laser with (drill drilling drilled)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 15:36
124	80	substrate with ((through adj hole) vias opening) with laser with (drill drilling drilled) with (conductive contact)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 15:52
125	76	(substrate with ((through adj hole) vias opening) with laser with (drill drilling drilled) with (conductive contact)) not ((438/629 438/667 438/668 438/672 438/675) and (laser nearl beam))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/28 15:53
126	29	5493096.URPN.	USPAT	2003/02/28 16:30
127	28	("3956052" "4168992" "4170490" "4304624" "4354107" "4403238" "4551629" "4618763" "4646128" "4703170" "4706166" "4764846" "4792672" "4794092" "4857477" "4870031" "4948941" "4956694" "4978420" "4992393" "4992908" "5013687" "5100501" "5213876" "5315147" "5316803" "5360491" "5451291").PN.	USPAT	2003/02/28 16:32